

SOT893-1

plastic low profile fine-pitch ball grid array package; 240 balls; body 11 x 11 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA240
Package type industry code	LFBGA240
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		10.9	-	11	11.1	mm
E	package width		10.9	-	11	11.1	mm
A	seated height		[tbd]	-	1.4	1.4	mm
A ₂	package height		0.9	-	1	1.1	mm
n ₂	actual quantity of termination		-	-	240	-	



2. Package outline

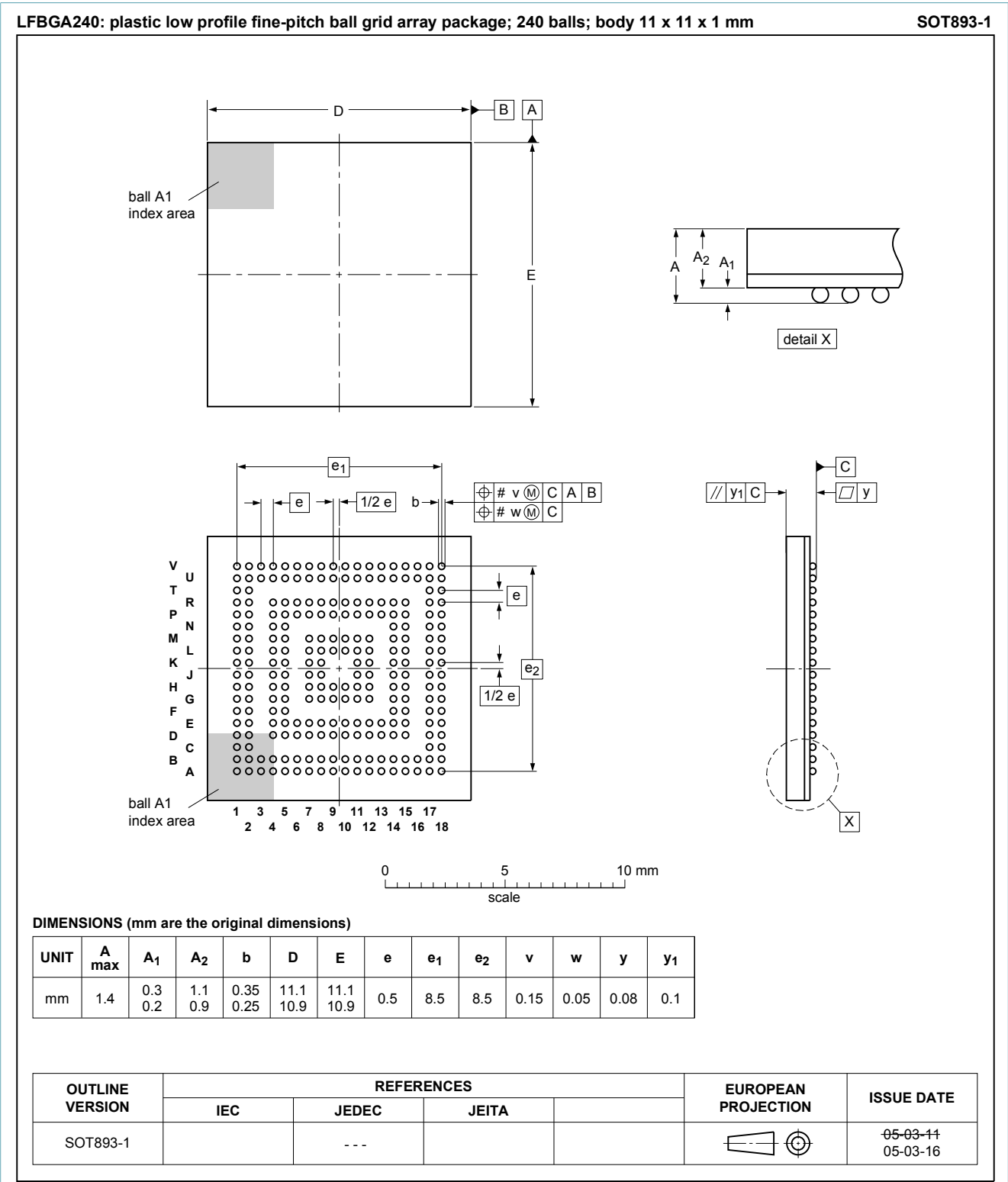


Fig. 1. Package outline LFBGA240 (SOT893-1)

3. Soldering

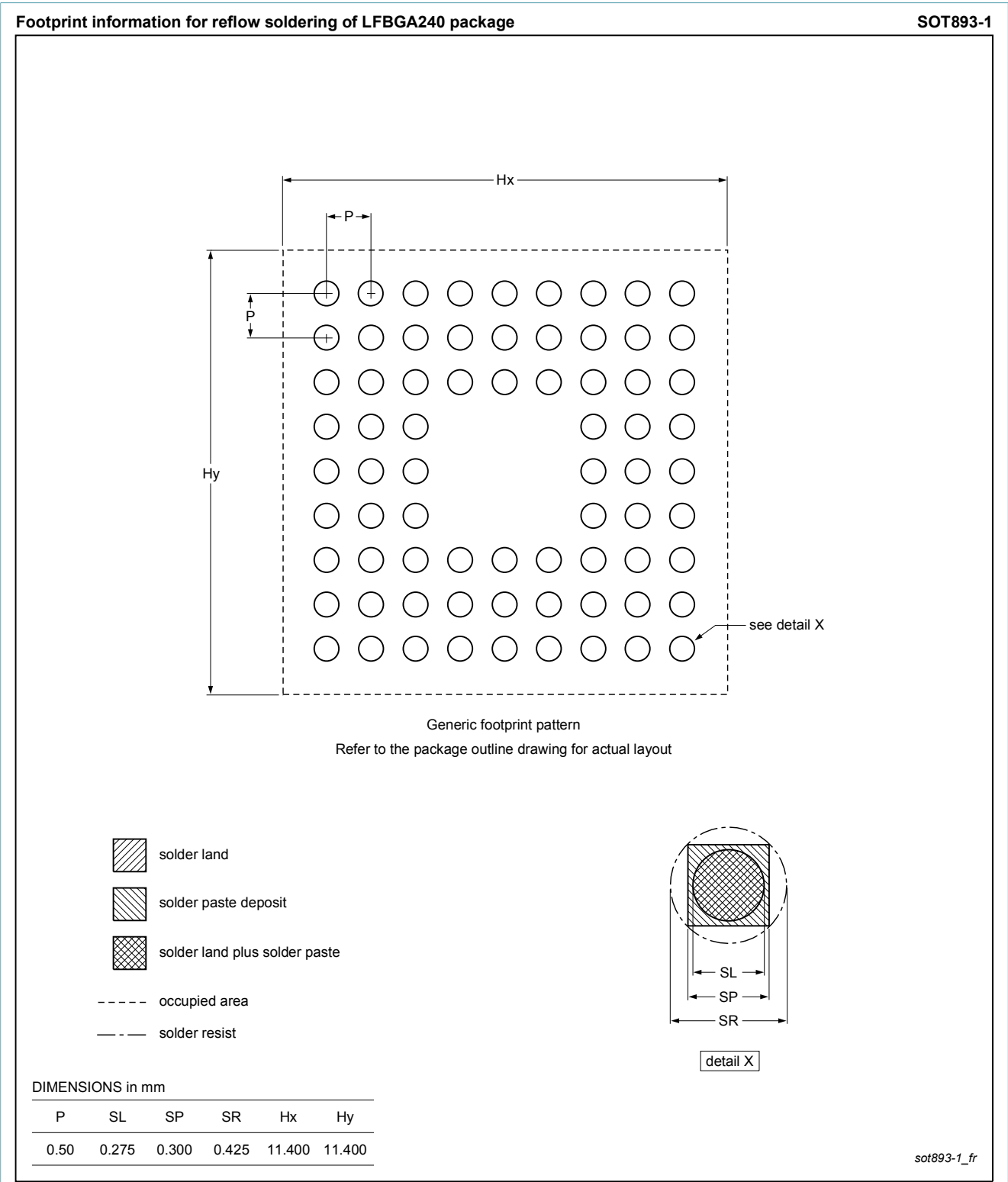


Fig. 2. Reflow soldering footprint for LFBGA240 (SOT893-1)

4. Legal information

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